

presented claimed a “polishing apparatus which imparts relative motion between a layer with a concave portion and a convex portion on a semiconductor wafer and a polishing tool.” Inherently, the surface of a semiconductor wafer is generally planar. Applicants are aware of none that are, for example cylindrical. Thus, the planar nature of the polishing surface is implicit and the proposed amendments only make explicit what was previously implicit. Thus, it is believed that entry at this time is proper.

The cited reference McHugh et al. (U.S. P. 5,647,788) discloses a grinding machine having a dressing tool (3) for dressing the grinding surfaces of grinding wheels (G). The shape of a grinding wheel of the wheels is columnar. The shape of the dressing tool is also columnar. Therefore, a cylindrical surface of the grinding wheel (G) is dressed by a cylindrical surface of the dressing tool (3). This is shown in Figs. 2, 3 and 13. On the other hand, the polishing surface of a polishing tool and the dressing surface of the dressing tool are planar as now claimed. Thus, McHugh does not meet the limitations of the claims as they are proposed to be amended. Nor, for the reasons noted above concerning the inherent planar nature of the claimed arrangement, did it meet them previously. The apparatus of McHugh is not adapted to polish a semiconductor wafer.

With entry of this amendment it is believed that all claims remaining in this application will be in condition for allowance. Thus, entry of this amendment and prompt notice is respectfully solicited.

Attached hereto is a marked-up version of the changes made to claims by the current amendment. The attached page is captioned **“Version With Markings To Show Changes Made.”**

The Examiner is invited to contact the undersigned to discuss any matter concerning this application.

Applicants respectfully request a three month Extension of Time to respond to the Final Rejection of October 22, 2001. The extended period expires April 22, 2002.

**"Version With Markings To Show Changes Made"**

Please amend claims 1 and 10 as follows:

1. (Twice Amended) A polishing apparatus which imparts relative motion between a layer with a concave portion and a convex portion on a semiconductor wafer and a polishing tool having a plane polishing surface to polish the surface of said workpiece by said plane [a] polishing surface of said polishing tool, comprising:

a dressing tool having a plane dressing surface for forming a surface roughness on the plane polishing surface of said polishing tool;

a first moving means for imparting relative motion in a direction horizontal to the plane polishing surface of said polishing tool between said dressing tool and said polishing tool;

a second moving means for moving said dressing tool in a direction vertical to the plane polishing surface of said polishing tool; and

a control means for permitting to execute movement caused by said first moving means while controlling a position of said second moving means.

10. (Twice Amended) A polishing apparatus which imparts relative motion between a layer with a concave portion and a convex portion and a polishing tool having a plane polishing surface to polish the surface of said workpiece by the plane polishing surface of said polishing tool, comprising:

a dressing tool having a plane dressing surface for forming a surface roughness on the plane polishing surface of said polishing tool; and

a means for inhibiting movement of said dressing tool [a grindstone] in a direction vertical to the polishing surface of said polishing tool.

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